

What is claimed is:

1. A method of manufacturing a device package in which a device is electrically connected to external wiring through a metal wire, said method comprising:

5 forming a small-diameter ball by using a small-diameter metal wire, bonding said small-diameter ball to said device, and then separating said small-diameter metal wire from said small-diameter ball;

10 forming a large-diameter ball by using a large-diameter metal wire, and bonding said large-diameter ball to said external wiring; and

15 bonding said large-diameter metal wire connecting with said large-diameter ball to said small-diameter ball by stitch bonding, and then separating said large-diameter metal wire from said small-diameter ball.

2. The method according to claim 1, wherein the diameter of said large-diameter metal wire is approximately equal to the diameter of said small-diameter ball.

3. The method according to claim 2, wherein said large-diameter metal wire is bonded to said small-diameter ball such that the height of the top portion of said large-diameter metal wire is approximately equal to the height of said small-diameter ball.

25 4. A device package in which a device is electrically connected to external wiring through a metal wire, said

device package comprising:

a small-diameter ball which is bonded to said device;
and

a large-diameter ball which is bonded to said external
5 wiring; wherein said small-diameter ball is connected to
said large-diameter ball through said metal wire while the
height of said small-diameter ball is approximately equal
to the height of said metal wire.